



DESCRIPTION

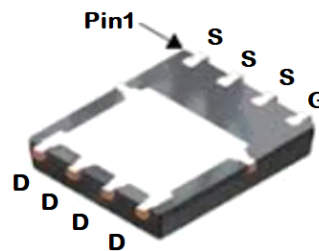
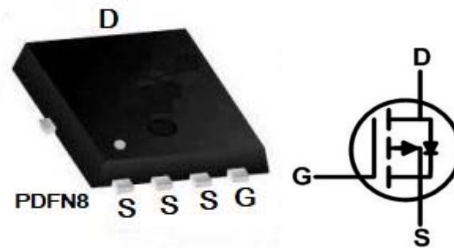
The AM80P04 is available in PDFN8(5×6) Package.

BVDSS	RDSON	ID
-40V	4.3mΩ	-80A

FEATURE

- Fast Switching
- $R_{DS(ON), typ.} = 4.3m\Omega @ V_{GS} = -10V$
- Low On-Resistance
- Low Gate Charge
- Low Reverse transfer capacitances
- High avalanche ruggedness

PIN DESCRIPTION



ORDERING INFORMATION

Package Type	Part Number	
PDFN8 (5×6) SPQ:5,000pcs /Reel	PJ8	AM80P04PJ8R
		AM80P04PJ8VR
Note	V: Halogen free Package R: Tape & Reel	
AiT provides all RoHS products		

Pin#	Symbol	Function
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

**ABSOLUTE MAXIMUM RATINGS**

T_A = 25°C, unless otherwise specified.

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	-40	V	
Gate-Source Voltage	V _{GS}	±20	V	
Continuous Drain Current, V _{GS} @ -10V ⁽¹⁾	I _D	T _A =25°C	-80	A
		T _C =100°C	-56	A
Pulsed Drain Current ⁽²⁾	I _{DM}	-320	A	
Single Pulse Avalanche Energy ⁽³⁾	E _{AS}	576	mJ	
Avalanche Current	I _{AS}	-56	A	
Total Power Dissipation ⁽⁴⁾	P _D	58	W	
Storage Temperature Range	T _{STG}	-55 to 175	°C	
Junction Temperature	T _J	175	°C	
THERMAL RESISTANCE				
Thermal Resistance Junction-ambient ⁽¹⁾ (t ≤ 10S)	R _{θJA}	20	°C/W	
Thermal Resistance Junction-ambient ⁽¹⁾ (Steady State)		50		
Thermal Resistance Junction-case ⁽¹⁾	R _{θJC}	1.6		

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

- (1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- (2) E_{AS} condition: T_A=25°C, V_{DD}=15V, V_G=-10V, R_g=25Ω, L=0.5mH.
- (3) Repetitive Rating: Pulse width limited by maximum junction temperature.
- (4) The power dissipation is limited by 150°C junction temperature



ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =+20V, V _{DS} =0V	-	-	±100	nA
ON CHARACTERISTICS						
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-20A	-	4.3	5.3	mΩ
		V _{GS} =-4.5V, I _D =-20A	-	5.9	7.6	mΩ
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.7	-2.5	V
Forward Transconductance	g _{fs}	V _{DS} =-5V, I _D =-20A	-	63	-	S
Dynamic CHARACTERISTICS						
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V, f=1.0MHz	-	6638	-	pF
Output Capacitance	C _{oss}		-	545	-	
Reverse Transfer Capacitance	C _{rss}		-	345	-	
Gate resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1.0MHz	-	2.2	-	Ω
Switching CHARACTERISTICS						
Turn-on Delay Time	t _{d(ON)}	V _{GS} =-10V, V _{DS} =-20V, R _L =1Ω, R _{GEN} =3Ω	-	16	-	nS
Rise Time	t _r		-	17	-	
Turn-Off Delay Time	t _{d(OFF)}		-	68	-	
Fall Time	t _f		-	31	-	
Total Gate Charge	Q _g	V _{GS} =-10V, V _{DS} =-20V, I _D =-20A	-	118	-	nC
Gate-Source Charge	Q _{gs}		-	13	-	
Gate-Drain Charge	Q _{gd}		-	22	-	
Source-Drain Diode CHARACTERISTICS						
Source-Drain Current (Body Diode)	I _S		-	-	-80	A
Forward on Voltage ⁽³⁾	V _{SD}	V _{GS} =0V, I _S =-20A	-	-	-1.2	V
Reverse Recovery Time	t _{rr}	I _F =-20A, di/dt=500A/μs	-	24	-	ns
Reverse Recovery Charge	Q _{rr}		-	140	-	nC

(3) Repetitive Rating: Pulse width limited by maximum junction temperature.



TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Output Characteristics

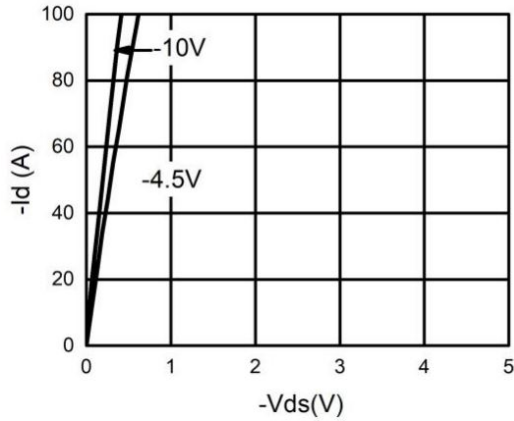


Fig 2. Transfer Characteristics

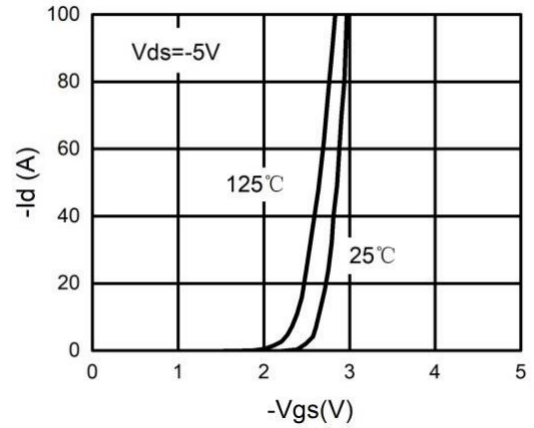


Fig 3. Power Dissipation

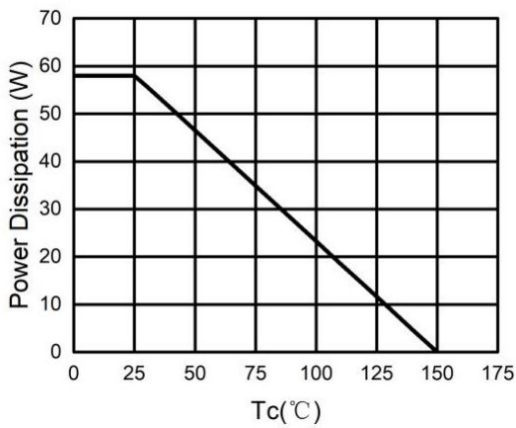


Fig 4. Drain Current

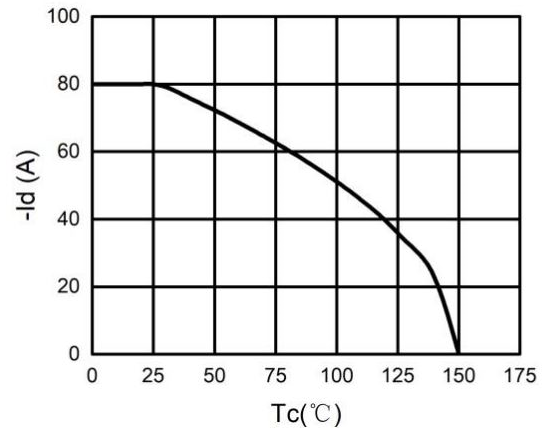


Fig 5. BVDSS vs Junction Temperature

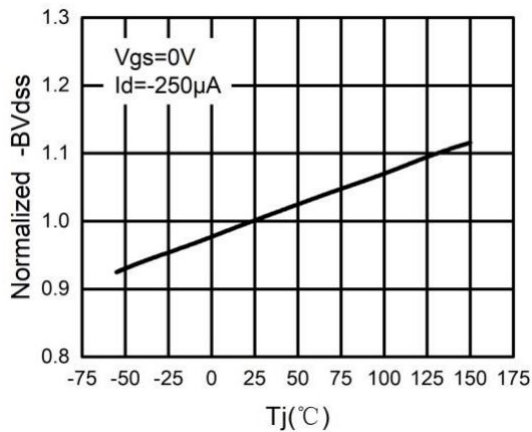


Fig 6. RDS(ON) vs Junction Temperature

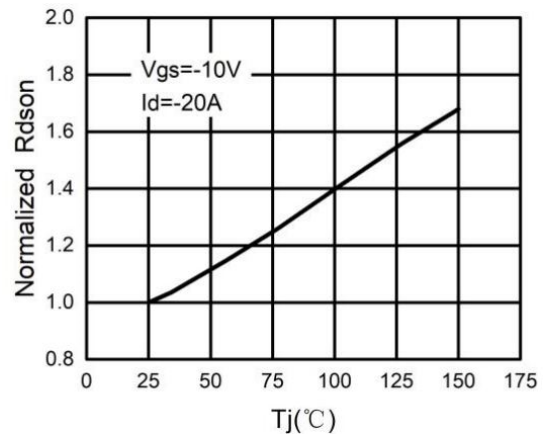




Fig7. Gate Charge Waveforms

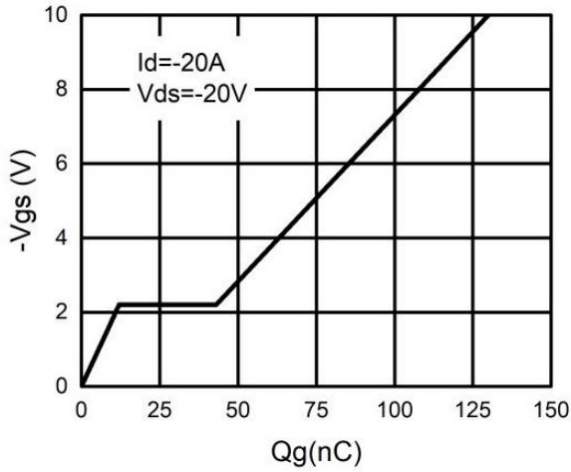


Fig 8. Capacitance

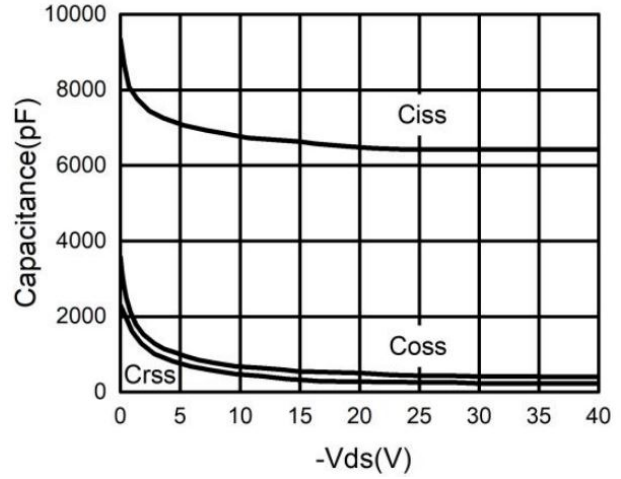


Fig 9. Body-Diode Characteristics

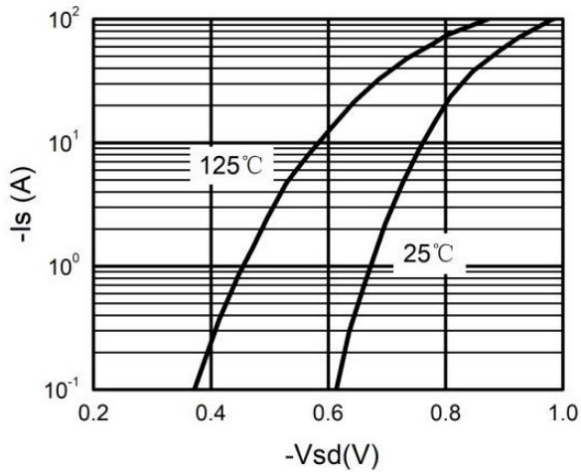


Fig 10. Maximum Safe Operating Area

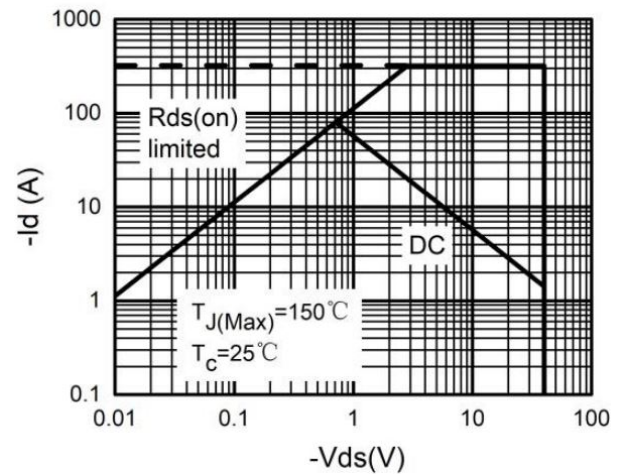


Fig 11. EAS Test Circuits

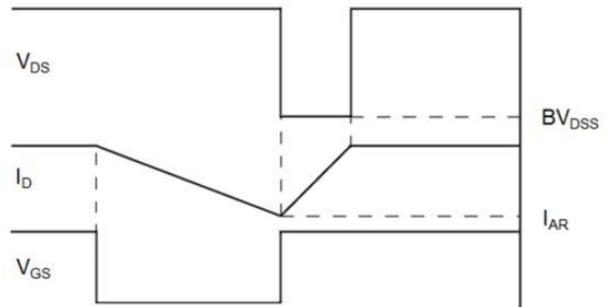
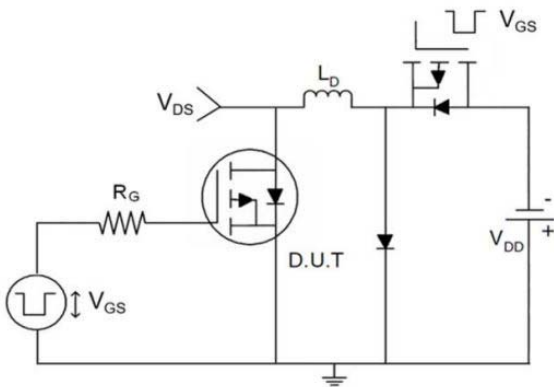




Fig 12. Gate Charge Test Circuit

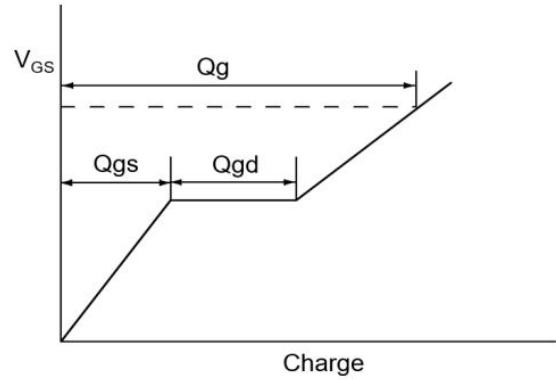
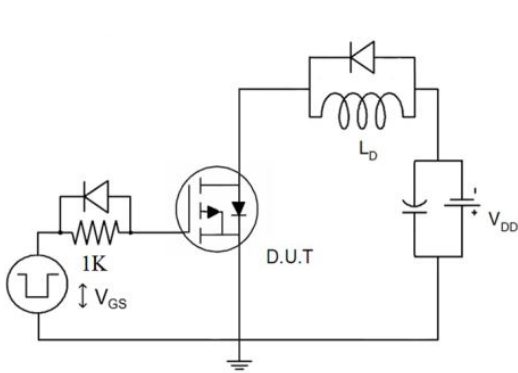
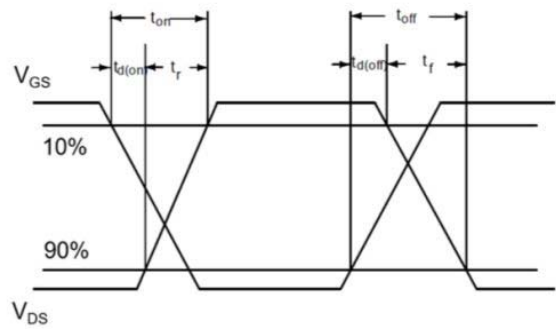
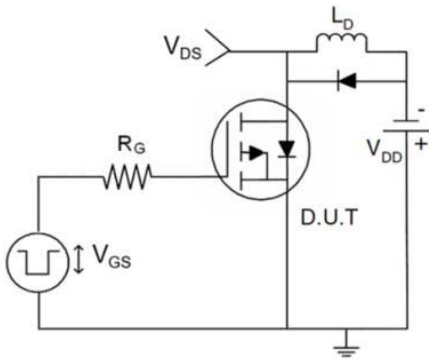


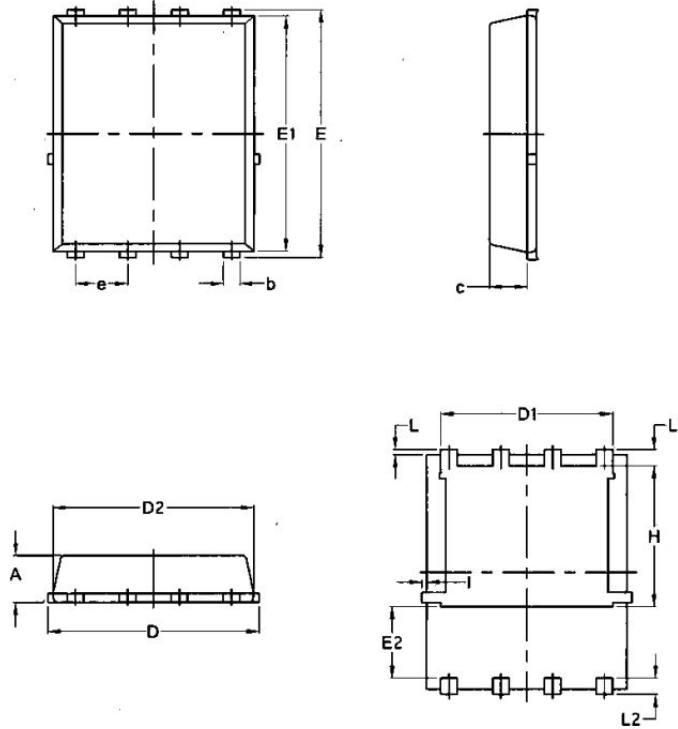
Fig 13. Switch Time Test Circuit





PACKAGE INFORMATION

Dimension in PDFN8 (5×6) (Unit: mm)



Symbol	Min.	Max.
A	1.0300	1.1700
b	0.3400	0.4800
c	0.8240	0.0970
D	4.8000	5.4000
D1	4.1100	4.3100
D2	4.8000	5.0000
E	5.9500	6.1500
E1	5.6500	5.8500
E2	1.6000	-
e	1.27BSC	
L	0.0500	0.2500
L1	0.3800	0.5000
L2	0.3800	0.5000
H	3.3000	3.5000
I	-	0.1800



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